

SHIELDING MEMBER OF PROCESSING SYSTEM

ABSTRACT OF THE DISCLOSURE

A shielding member applicable in a deposition apparatus is provided. The shielding member includes a base metal and an adhesion promoter layer arc-sprayed on the base metal, wherein adhesion promoter layer has a thickness gradient increasing from an upper end of the shielding member to a lower end of the shielding member. More preferably, no adhesion promoter layer is formed in the upper 10 cm of the shielding member, adjacent to a target layer.

(Fig. 1)